
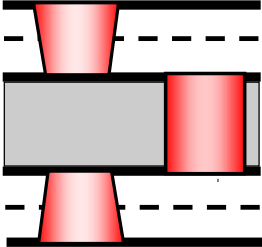


<b>Build Up HDI (Standard)</b>		
HDI04_1+2b+1_0,80_engl		
<b>4 - Layers</b> Core: 0,61 mm Cu 35/35 µm		
<b>WE-Articel No.:</b>		<b>1 + 2B + 1</b>
<b>Customer:</b>		

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements	
Customer	WE					[µm]	[µm]	
	TOP/VS		Foil	12 µm	1)	12		
						1 x 1080	60	
	2				12 µm		35	
				0,610 mm			610	
	3				12 µm		35	
						1 x 1080	60	
	BOT/RS			Foil	12 µm	1)	12	
1) copper thickness outer layers: appr. 55 µm								
total material thickness:						824		
<small>Note: Lamination thickness for Prepregs depending on layout characteristics.</small>								

<b>final lamination thickness:</b>	<b>0,80</b>	+/-	0,07	mm			Date:	Engineer:
thickness with electro plated Cu:	0,89	+/-	0,10	mm				
total thickness with soldermask	0,95	+/-	0,12	mm				
customer requirement		+/-		mm	point:			
prepared: on 04.01.2006	by S. Keller	checked: on 04.05.2006	by M.Kress	approved: on 04.01.2006	by R. Schönholz	revision 00	page: 8-	